Heterogeneous Integration Roadmap Workshop
ESTC

Dresden September 19th 2018
13:00 - 16:30

Welcome to the Heterogeneous Integration Roadmap Workshop hosted by the 2018 ESTC Conference.

Our Industry has reinvented itself through multiple disruptive changes in technologies, products and markets.. With the rapid migration of logic, memory and applications to the Cloud infrastructures, Data Centers and 5G Networks, the Internet of Things (IoT) to internet of everything (IOE), Autonomous Vehicles, the proliferation of Smart Devices every where, and increasing interest in 5G, artificial intelligence (AI) & Virtual Reality (VR) , the pace of innovation is increasing to meet these challenges. What are the paths forward?

The IEEE Heterogeneous Integration Technology Roadmap (HIR), is sponsored by the IEEE Electronic Packaging Society (EPS), the Electron Devices Society (EDS), Photonics Society together with ASME EPPD and SEMI. It will address the future directions of heterogeneous integration technologies and applications serving future markets and applications, so very crucial to our profession, our industries, academic and research communities. Following the spirit of ITRS, the HIR is a pre-competitive technology roadmap provides long-term vision to identify the needs of future technology challenges, roadblocks, and potential solutions focused on system integration and broad market applications in order to accelerate progress for the broad electronics industry.

Heterogeneous Integration Roadmap Workshop at ESTC

Agenda

September 19, 2018 13:00 – 16:00

Welcome Messages	Hubert Lakner & Karlheinz Bock
Invited Talk (19 min each talk)	
• Heterogeneous Integration Roadmap Overview	Bill Chen & Bill Bottoms
• Opportunities & Challenges in Automotive Electronics Packaging	Andreas Middendorf
• Photonics Integration	Gunnar Böttger
• ITRW & Power Electronics Integration	Pete Wilson & Jing Zhang
Heterogeneous Integration Roadmap TWG Session (11 minutes each talk)	
TWG Session Co - Moderators :	Jean Trewhella & Klaus Pressel
• System-in-Package (SIP)	Rolf Aschenbrenner
• WLP & Fanout	John Hunt
• Co-Design & Simulations	Chris Bailey
• 5G & Analog & Mixed Signal	Frank Fitzek
Panel (all speakers) Q&A Session	
Wrap-Up	Bill Bottoms & Bill Chen

IEEE

IEEE photonics Society

semi

CPMT IEEE COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY SOCIETY

ASME

ELECTRON DEVICES SOCIETY